















ESD

TVS

MOS

LDO

Diode

Sensor

DC-DC

Product Specification

Domestic Part Number	IRFZ48NS
Overseas Part Number	IRFZ48NS
▶ Equivalent Part Number	IRFZ48NSTRL





Description

The IRFZ48NS uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

Application

Battery protection

Load switch

Uninterruptible power supply

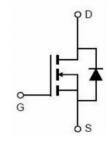
General Features

V_{DS} = 60V I_D =50A

 $R_{DS(ON)} < 12 m\Omega$ @ $V_{GS}=10V$

 $R_{DS(ON)} < 15 m\Omega$ @ $V_{GS} = 4.5 V$

TO-263 Pin Configuration



Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units	
Vos	Drain-Source Voltage	60	V	
Vgs	Gate-Source Voltage	±20	V	
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	50	Α	
Ip@Tc=100°C	Continuous Drain Current, V _{GS} @ 10V ¹	25	Α	
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	7.4	Α	
ID@TA=70°C	Continuous Drain Current, V _{GS} @ 10V ¹	6	А	
Ірм	Pulsed Drain Current ²	90	А	
EAS	Single Pulse Avalanche Energy ³	39.2	mJ	
las	Avalanche Current	28	Α	
Pp@Tc=25°C	Total Power Dissipation ⁴	45	W	
PD@TA=25°C	Total Power Dissipation ⁴	2	W	
Тѕтс	Storage Temperature Range	-55 to 150	°C	
Tj	Operating Junction Temperature Range	-55 to 150	°C	
ReJA	Thermal Resistance Junction-Ambient ¹	62	°CM	



Reuc Thermal Resistance Junction-Case ¹ 2.8	٧
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Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVpss	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	60			V
∆BV _{DSS} /∆T _J	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =1mA		0.057		V/°C
	V _{GS} =10V , I _D =20A		10	13		
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =10A		12	15	mΩ
VGS(th)	Gate Threshold Voltage		1.2		2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	V _{GS} =V _{DS} , I _D =250uA		-5.68		mV/°C
		V _{DS} =48V , V _{GS} =0V , T _J =25°C			1	
loss	Drain-Source Leakage Current	V _{DS} =48V , V _{GS} =0V , T _J =55°C			5	uA
Igss	Gate-Source Leakage Current	V_{GS} = $\pm 20V$, V_{DS} = $0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =15A		45		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.7		Ω
Qg	Total Gate Charge (4.5V)			19.3		
Qgs	Gate-Source Charge	V _{DS} =48V , V _{GS} =4.5V , I _D =15A		7.1		nC
Q_{gd}	Gate-Drain Charge			7.6		
T _{d(on)}	Turn-On Delay Time	V _{DD} =30V , V _{GS} =10V , —R _G =3.3 , —I _D =15A		7.2		7
Tr	Rise Time			50		ns
Td(off)	Turn-Off Delay Time			36.4		
T _f	Fall Time			7.6		
Ciss	Input Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		2423		
Coss	Output Capacitance			145		pF
Crss	Reverse Transfer Capacitance			97		
Is	Continuous Source Current ^{1,5}	V _G =V _D =0V , Force Current	1		35	Α
lsм	Pulsed Source Current ^{2,5}				80	Α
VsD	Diode Forward Voltage ²	V _{GS} =0V , I _S =A , T _J =25°C			1	V
t _{rr}	Reverse Recovery Time	V = 1999-05-0		16.3		nS
Qrr	Reverse Recovery Charge	IF=15A , dI/dt=100A/μs , T _J =25°C		11		nC

Note:

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width \leqq 300us , duty cycle \leqq 2%
- 3.The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=28A
- 4.The power dissipation is limited by 150°C junction temperature 5.The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation



Typical Characteristics

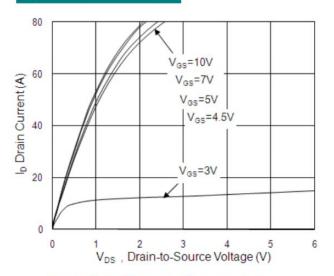


Fig.1 Typical Output Characteristics

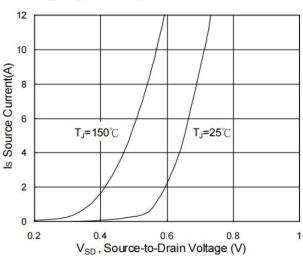


Fig.3 Forward Characteristics of Reverse

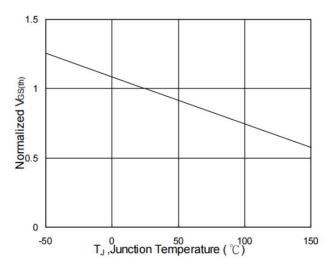


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

60V N-Channel Enhancement Mode MOSFET

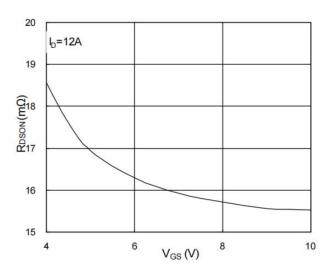


Fig.2 On-Resistance v.s Gate-Source

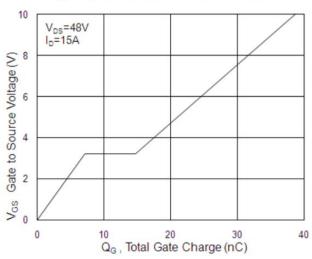


Fig.4 Gate-Charge Characteristics

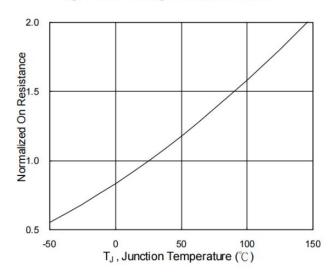
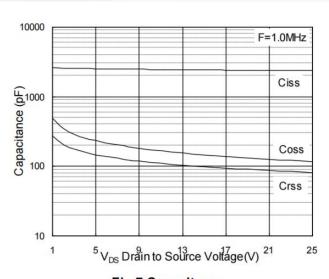


Fig.6 Normalized R_{DSON} v.s T_J





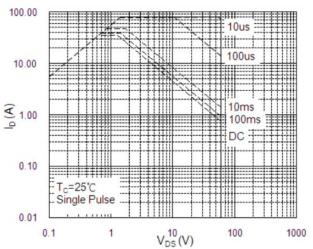


Fig.7 Capacitance

Fig.8 Safe Operating Area

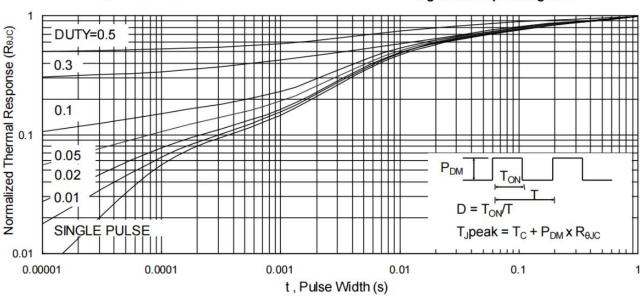


Fig.9 Normalized Maximum Transient Thermal Impedance

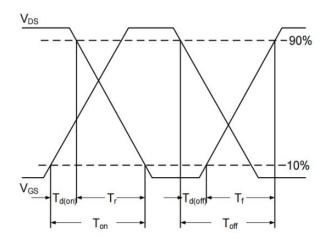


Fig.10 Switching Time Waveform

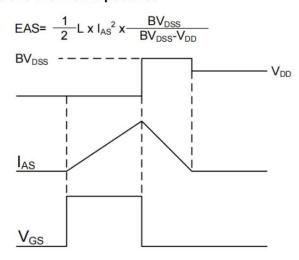
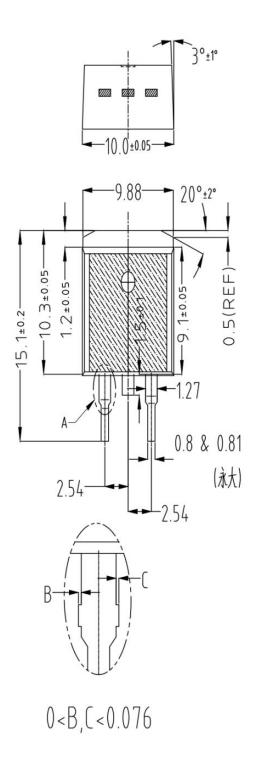


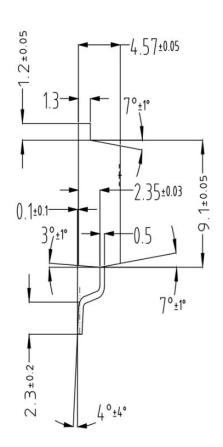
Fig.11 Unclamped Inductive Switching Waveform

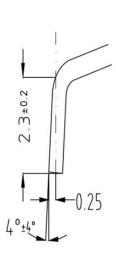


TO-263 Package Outline Dimensions

Package Outline Dimensions (Units: mm)









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